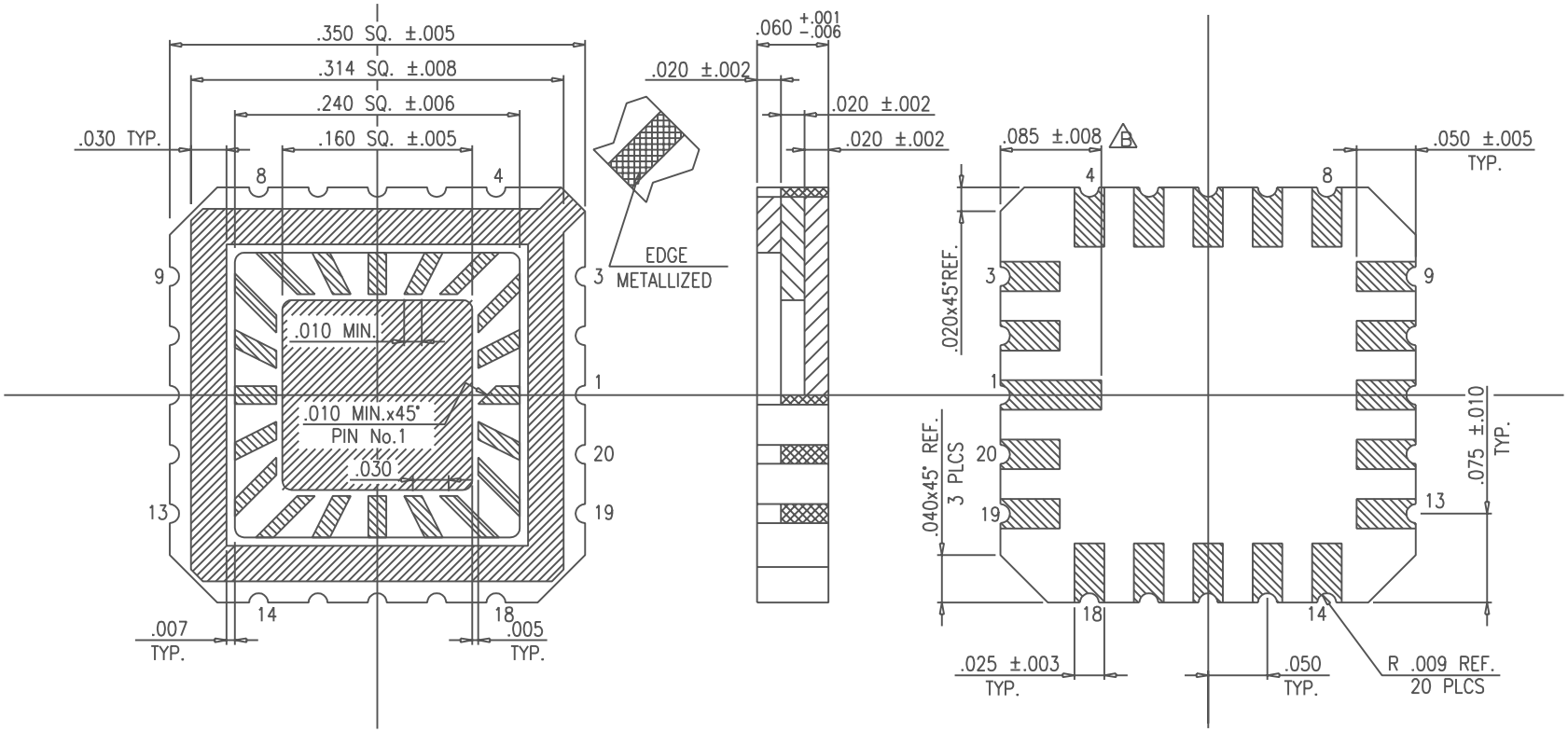
SSM P/N LCC02020



NOTES:

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN. THICHKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003.
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

MODIFICATIONS					
B	CHANGED : PATTERN	'82-12-16	M.M	O.M	
A	CHANGED : TORERANCES	'82-2-5	O.M	N.U	
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 20 LEAD CHIP CARRIER		TOLERANCES: UNLESS OTHERWISE SPECIFIED ± .005 THIRD ANGLE PROJECTION	HG-20CAX	
SCALE 10/1	MATERIAL KYOCERA A-440		DRAWN A.N	CHECKED O.M Y.S
KYOCERA	KYOCERA CORPORATION KYOTO JAPAN		APPROVED	DATE '81-3-6
			DRAWING NO. PB-12884-B	SHEET /

PB-92149-A MOD.

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408.435.5555 Fax: 408.435.8226